

# DATA SHEET

## **74ALS174** Hex D flip-flop

Product specification

1991 Feb 08

IC05 Data Handbook

# Hex D flip-flop

# 74ALS174

## FEATURES

- Four edge-triggered D flip-flops
- Buffered common clock
- Buffered asynchronous master reset

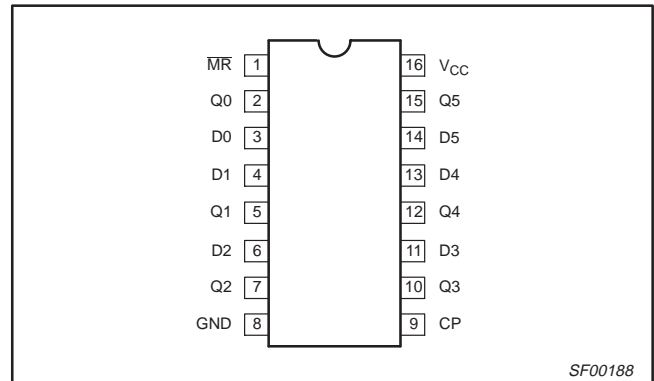
## DESCRIPTION

The 74ALS174 has six edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered clock (CP) and master reset ( $\overline{MR}$ ) inputs load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the Low-to-High clock transition is transferred to the corresponding flip-flop's Q output.

All Q outputs will be forced Low independent of clock or data inputs by a Low voltage level on the  $\overline{MR}$  input. The device is useful for applications where true outputs only are required, and the clock and master reset are common to all storage elements.

## PIN CONFIGURATION



SF00188

## ORDERING INFORMATION

DESCRIPTION	ORDER CODE	DRAWING NUMBER
	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$ , $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$	
16-pin plastic DIP	74ALS174N	SOT38-4
16-pin plastic SO	74ALS174D	SOT109-1

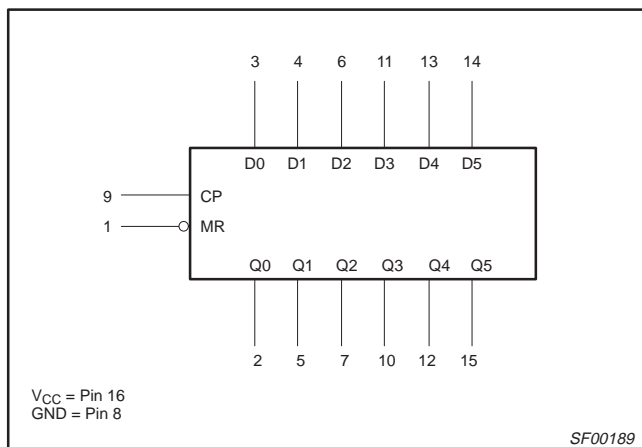
TYPE	TYPICAL $f_{MAX}$	TYPICAL SUPPLY CURRENT (TOTAL)
74ALS174	70MHz	7mA

## INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74ALS (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0 – D3	Data inputs	1.0/1.0	20 $\mu$ A/0.1mA
CP	Clock Pulse input (active rising edge)	1.0/1.0	20 $\mu$ A/0.1mA
$\overline{MR}$	Master Reset input (active-Low)	1.0/1.0	20 $\mu$ A/0.1mA
Q0 – Q5	Data outputs	20/80	0.4mA/8mA

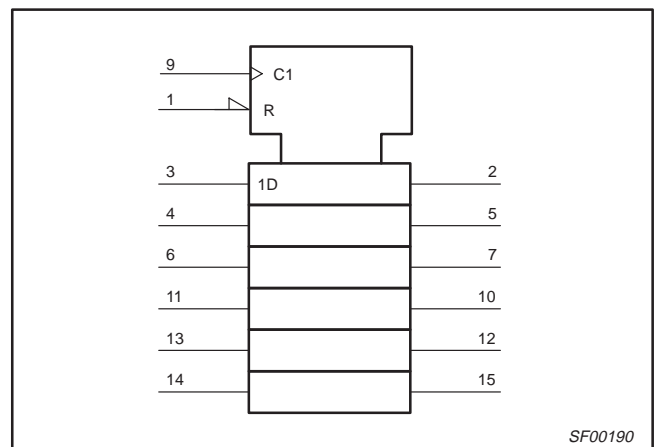
**NOTE:** One (1.0) ALS unit load is defined as: 20 $\mu$ A in the High state and 0.1mA in the Low state.

## LOGIC SYMBOL



SF00189

## IEC/IEEE SYMBOL

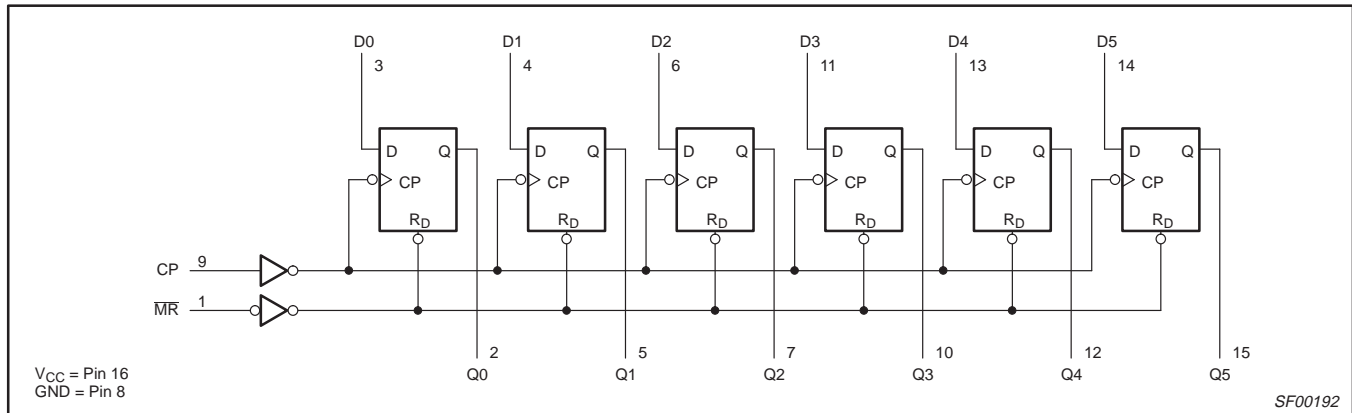


SF00190

# Hex D flip-flop

74ALS174

## LOGIC DIAGRAM



## FUNCTION TABLE

INPUTS			OUTPUTS	OPERATING MODE
MR	CP	D	Q <sub>n</sub>	
L	X	X	L	Reset (clear)
H	↑	h	H	Load "1"
H	↑	l	L	Load "0"

### NOTES:

- H = High-voltage level
- h = High state must be present one setup time before the Low-to-High clock transition
- L = Low-voltage level
- l = Low state must be present one setup time before the Low-to-High clock transition
- X = Don't care
- ↑ = Low-to-High clock transition

## ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to V <sub>CC</sub>	V
I <sub>OUT</sub>	Current applied to output in Low output state	16	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-0.4	mA
I <sub>OL</sub>	Low-level output current			8	mA
T <sub>amb</sub>	Operating free-air temperature range	0		+70	°C

## Hex D flip-flop

74ALS174

**DC ELECTRICAL CHARACTERISTICS**

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS <sup>1</sup>	LIMITS			UNIT
			MIN	TYP <sup>2</sup>	MAX	
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> ±10%, V <sub>IL</sub> = MAX, V <sub>IH</sub> = MIN, I <sub>OH</sub> = MAX	V <sub>CC</sub> - 2			V
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, V <sub>IH</sub> = MIN	I <sub>OL</sub> = 4mA	0.25	0.4	V
			I <sub>OL</sub> = 8mA	0.35	0.50	V
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = I <sub>IK</sub>		-0.73	-1.5	V
I <sub>I</sub>	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7.0V			100	μA
I <sub>IH</sub>	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7V			20	μA
I <sub>IL</sub>	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5V			-0.1	mA
I <sub>O</sub>	Output current <sup>3</sup>	V <sub>CC</sub> = MAX, V <sub>O</sub> = 2.25V	-30		-112	mA
I <sub>CC</sub>	Supply current (total)	V <sub>CC</sub> = MAX		7	14	mA

**NOTES:**

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
- The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I<sub>OS</sub>.

**AC ELECTRICAL CHARACTERISTICS**

SYMBOL	PARAMETER	TEST CONDITION	LIMITS		UNIT
			T <sub>amb</sub> = 0°C to +70°C V <sub>CC</sub> = +5.0V ± 10% C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω		
			MIN	MAX	
f <sub>MAX</sub>	Maximum clock frequency	Waveform 1	60		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to Qn	Waveform 1	5.0 5.0	15.0 15.0	ns
t <sub>PHL</sub>	Propagation delay, $\overline{MR}$ to Qn	Waveform 2	8.0	18.0	ns

**AC SETUP REQUIREMENTS**

SYMBOL	PARAMETER	TEST CONDITION	LIMITS		UNIT
			T <sub>amb</sub> = 0°C to +70°C V <sub>CC</sub> = +5.0V ± 10% C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω		
			MIN	MAX	
t <sub>su(H)</sub> t <sub>su(L)</sub>	Setup time, High or Low Dn to CP	Waveform 3	6.0 6.0		ns
t <sub>h(H)</sub> t <sub>h(L)</sub>	Hold time, High or Low Dn to CP	Waveform 3	0.0 0.0		ns
t <sub>w(H)</sub> t <sub>w(L)</sub>	CP pulse width, High or Low	Waveform 1	8.0 8.0		ns
t <sub>w(L)</sub>	$\overline{MR}$ pulse width, Low	Waveform 2	6.0		ns
t <sub>REC</sub>	Recovery time, $\overline{MR}$ to CP	Waveform 2	6.0		ns

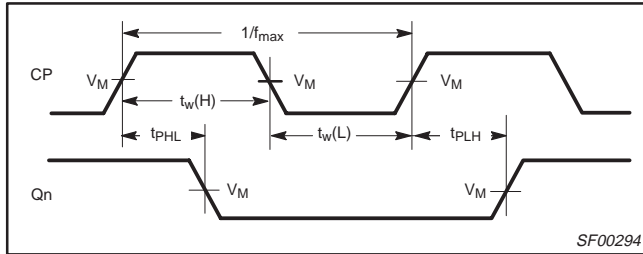
# Hex D flip-flop

74ALS174

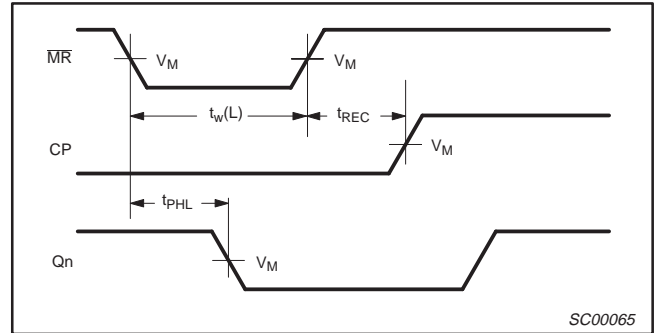
## AC WAVEFORMS

For all waveforms,  $V_M = 1.3V$ .

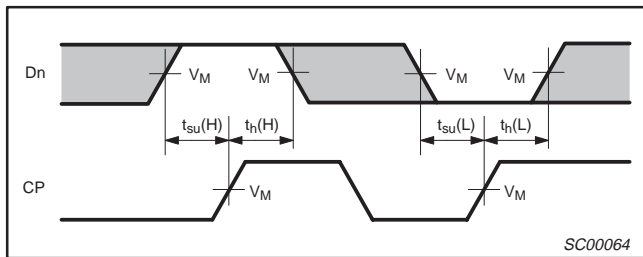
The shaded areas indicate when the input is permitted to change for predictable output performance.



**Waveform 1. Propagation Delay for Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency**

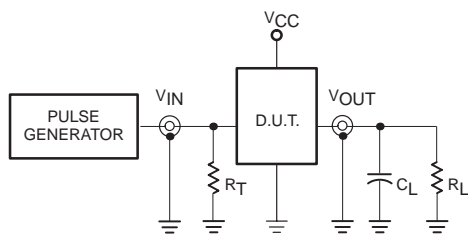


**Waveform 2. Master Reset Pulse Width, Master Reset to Output Delay, and Master Reset to Clock Recovery Time**



**Waveform 3. Data Setup and Hold Times**

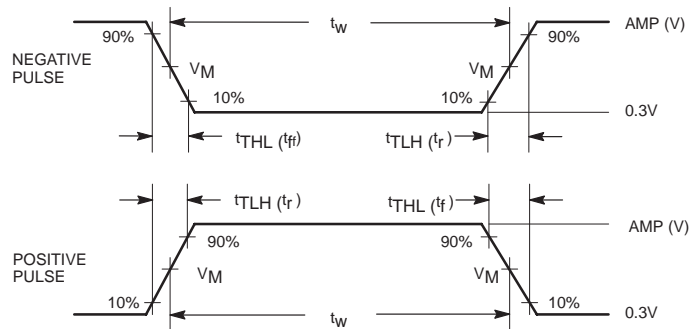
## TEST CIRCUIT AND WAVEFORMS



**Test Circuit for Totem-pole Outputs**

### DEFINITIONS:

- $R_L$  = Load resistor; see AC electrical characteristics for value.
- $C_L$  = Load capacitance includes jig and probe capacitance; see AC electrical characteristics for value.
- $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generators.



**Input Pulse Definition**

Family	INPUT PULSE REQUIREMENTS					
	Amplitude	$V_M$	Rep. Rate	$t_w$	$t_{TLH}$	$t_{THL}$
74ALS	3.5V	1.3V	1MHz	500ns	2.0ns	2.0ns

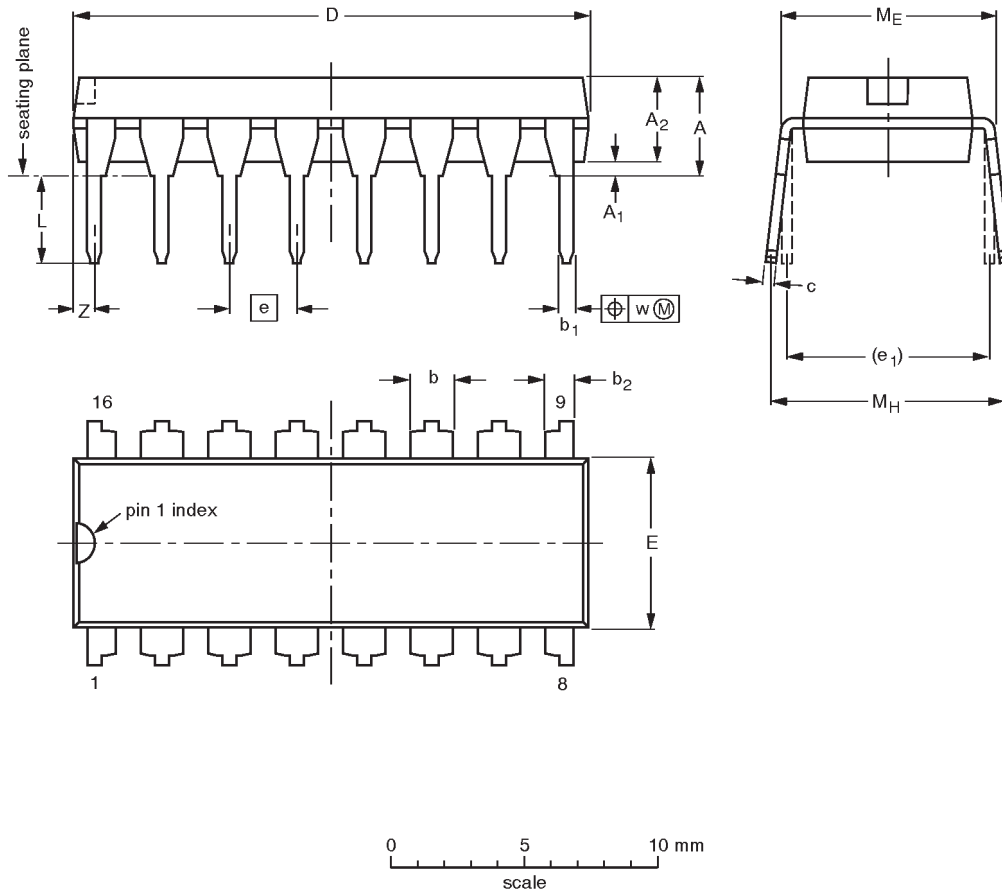
SC00005

# Hex D flip-flop

# 74ALS174

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

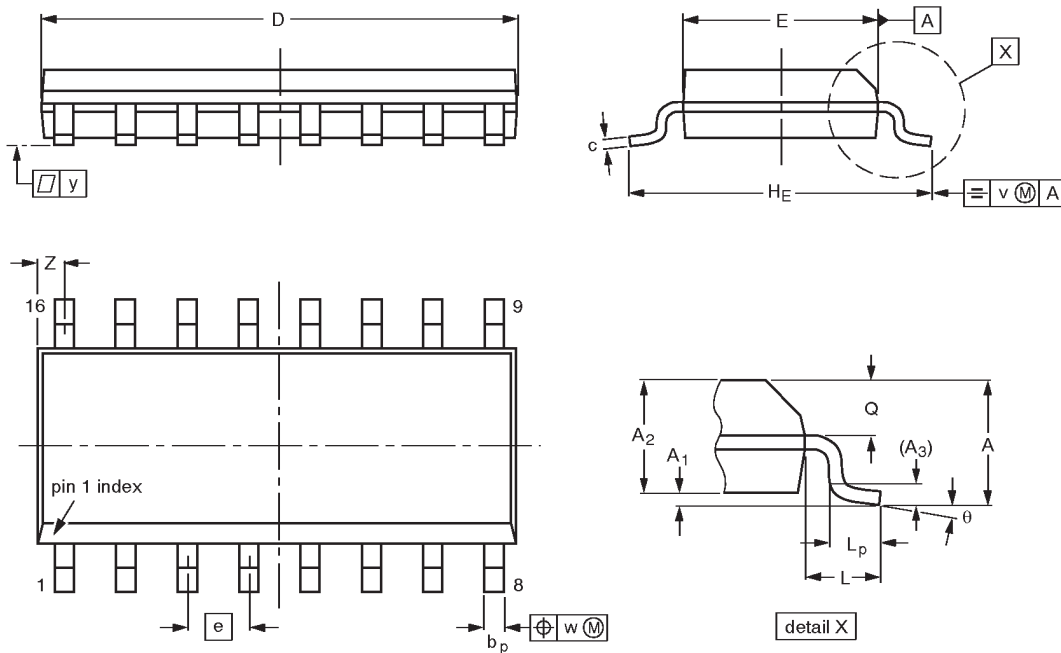
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-4						-92-11-17 95-01-14

# Hex D flip-flop

# 74ALS174

**SO16: plastic small outline package; 16 leads; body width 3.9 mm**

**SOT109-1**



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.0098 0.0039	0.057 0.049	0.01	0.019 0.014	0.0098 0.0075	0.39 0.38	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

**Note**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07S	MS-012AC				91-08-13 95-01-23

## Hex D flip-flop

74ALS174

## DEFINITIONS

Data Sheet Identification	Product Status	Definition
<i>Objective Specification</i>	<b>Formative or in Design</b>	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
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